



Material Content Data Sheet



Sales Product Name	BGB 717L7ESD E6327			Issued		29. August 2013		
MA#	MA000622748							
Package	PG-TSLP-7-1			Weight*		1.57 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.00		0	
	noble metal	gold	7440-57-5	0.007	0.00		0	
	inorganic material	silicon	7440-21-3	0.049	0.00		0	40497
leadframe	non noble metal	nickel	7440-02-0	0.329	0.00		0	209883
wire	noble metal	gold	7440-57-5	0.036	0.00		0	22873
encapsulation	organic material	carbon black	1333-86-4	0.011	0.00		0	
	plastics	epoxy resin	-	0.146	0.00		0	
	inorganic material	silicondioxide	60676-86-0	0.924	0.00		0	689940
leadfinish	noble metal	gold	7440-57-5	0.032	0.00		0	20195
plating	noble metal	gold	7440-57-5	0.032	0.00		0	20195
*deviation	< 10%	Sum in total:				0,00		1003583

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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